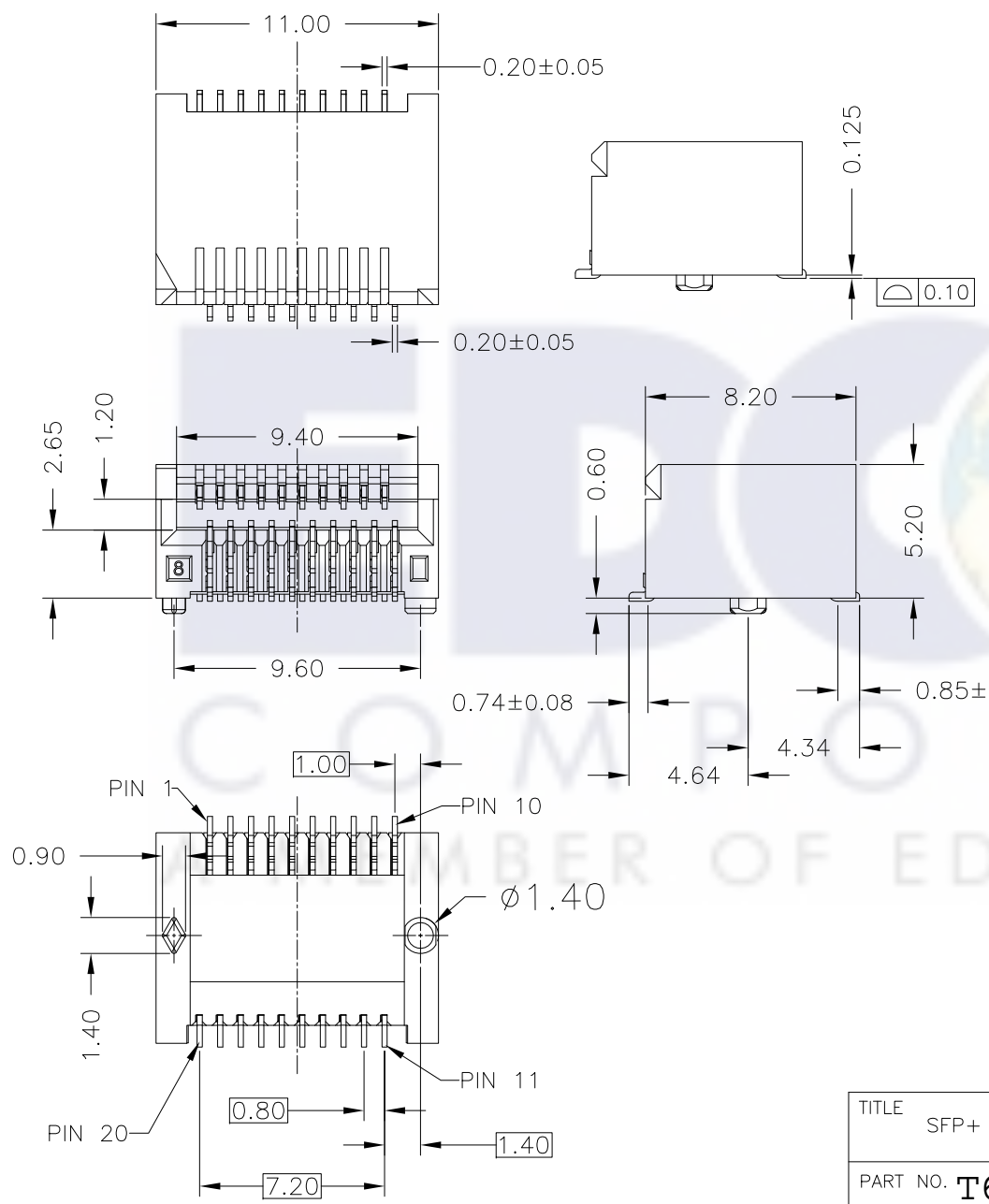


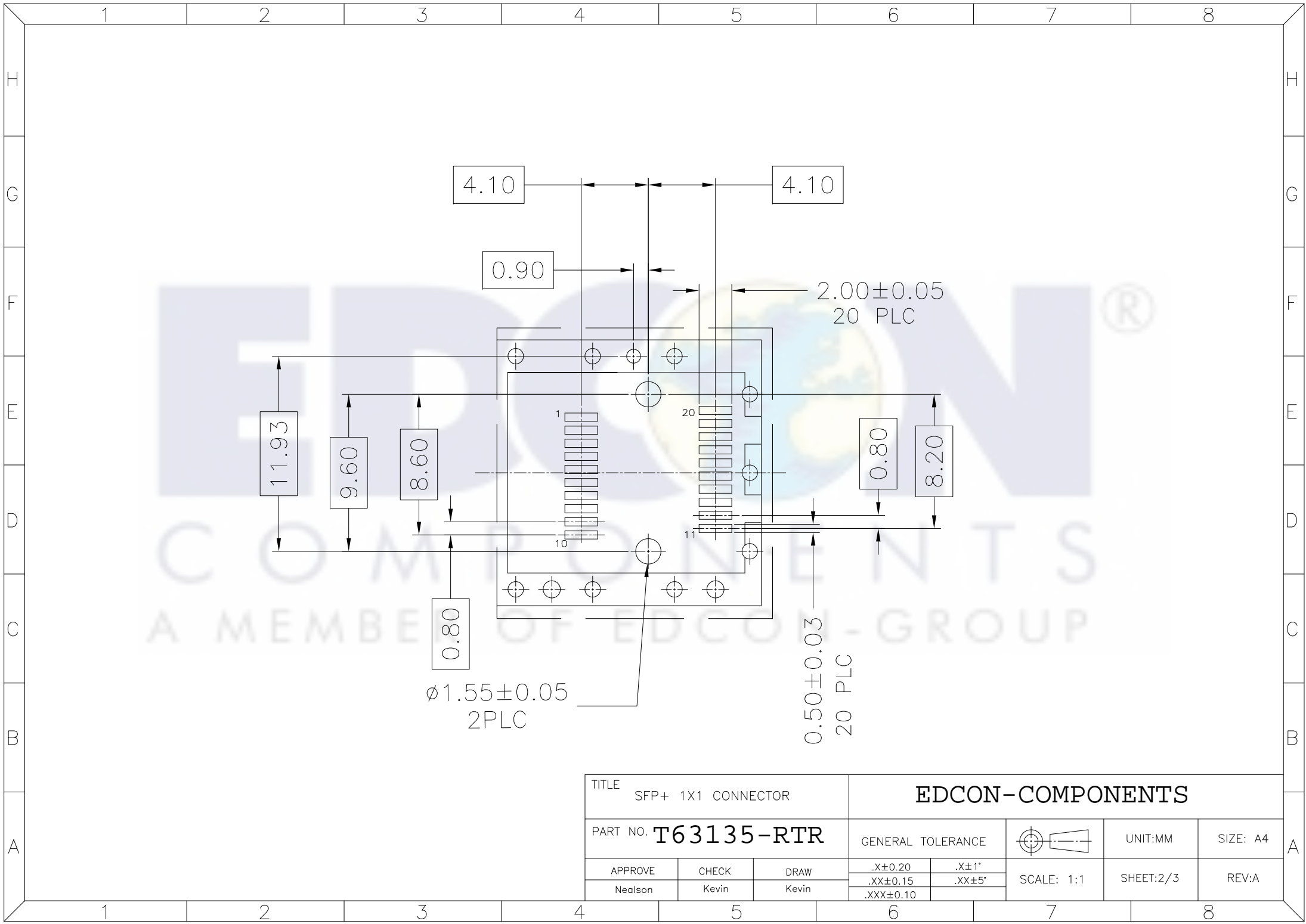
6	7	8	
REV	DESCRIPTION OF CHANGE	REVIEWED BY	ISSUE DATE
A	FIRST ISSUE	Nealson	2021-08-01

NOTES:

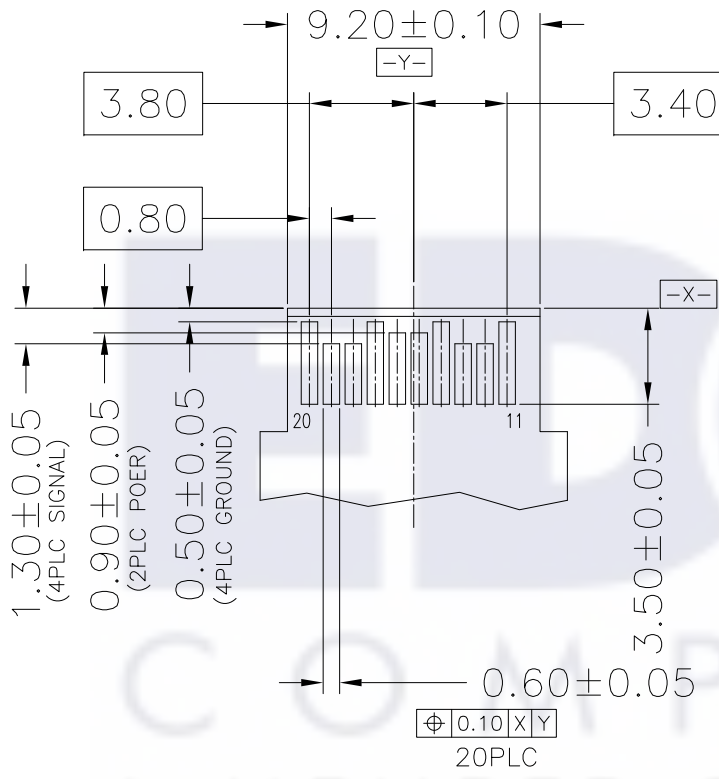
- 1.MATERIAL
HOUSING: HIGH TEMPERATURE LCP, Black, UL94 V-0.
- 2.CONTACTS: PHOSPHOR BRONZE
PLATING :15μ" GOLD ON MATING AREA,
GOLD FLASH PLATING ON
SOLDER TAILS, 50μ" NICKEL
UNDERPLATING OVERALL.
3. MECHANICAL REQUIREMENT:
3.1 DURABILITY:100 CYCLES NIN.
3.2 INSERTION AND EXTRACTION FORCE:40N MAX. & 11.5N MAX.
4. ENVIRONMENTAL:
4.1 CONTACT RESISTANCE:20 MILLIOHMS MAX INITIAL.
4.2 DIELECTRIC WITHSTANDING VOLTAGE: 300V AC/MIN.
4.3 CURRENT RATING: 0.5 Amps Max.
4.4 OPERATION: -40°C TO +95°C
4.5 STORAGE: -55°C TO +105°C
4.6 REFLOW SOLDERING TEMPERATURE: 255~265° MAXLIMUM
FOR 5~10 SECONDS.
4.9 ROHS COMPLIANT
- 5.PACKAGING: TAPE AND REEL



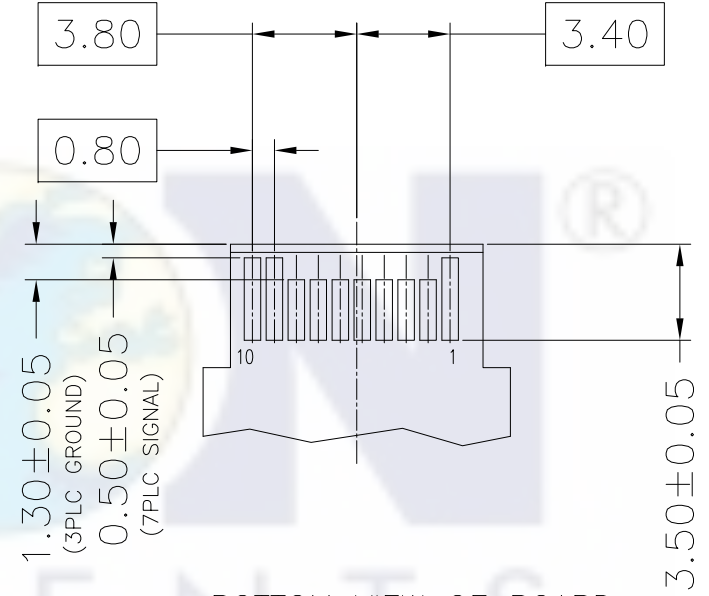
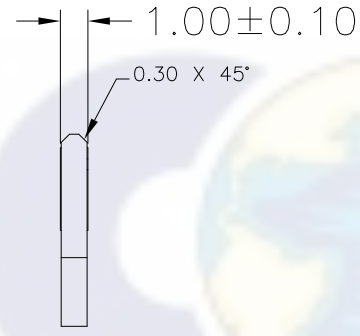
TITLE			EDCON-COMPONENTS				
SFP+ 1X1 CONNECTOR							
PART NO. T63135-RTR			GENERAL TOLERANCE			UNIT:MM	SIZE: A4
APPROVE	CHECK	DRAW	.X±0.20	.X±1'	SCALE: 1:1	SHEET:1/3	REV:A
Nealson	Kevin	Kevin	.XX±0.15	.XX±5'			
			.XXX±0.10				



TITLE			EDCON-COMPONENTS			
SFP+ 1X1 CONNECTOR						
PART NO. T63135-RTR			GENERAL TOLERANCE		UNIT:MM	SIZE: A4
APPROVE	CHECK	DRAW	.X±0.20	.X±1°	SCALE: 1:1	SHEET:2/3
Neelson	Kevin	Kevin	.XX±0.15	.XX±5°		
			.XXX±0.10			



TOP VIEW OF BOARD



BOTTOM VIEW OF BOARD

RECOMMENDED LAYOUT DETAIL MATING TRANSCEIVER PCB

TITLE SFP+ 1X1 CONNECTOR			EDCON-COMPONENTS			
PART NO. T63135-RTR			GENERAL TOLERANCE		UNIT:MM	SIZE: A4
APPROVE	CHECK	DRAW	.X±0.20	.X±1°	SCALE: 1:1	SHEET:3/3
Nealson	Kevin	Kevin	.XX±0.15	.XX±5°		
			.XXX±0.10			